

25 Gbps 1310 nm PIN

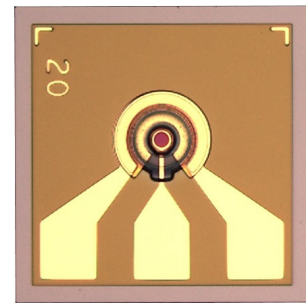
L-CR-IM99-00

Part Number: L-CR-IM99-00

Applications: 25 Gbps

Absolute Maximum Ratings (T = 25°C):

Parameter	Symbol	Unit	Value	Note
Forward Current	I_F	mA	10	
Reverse Voltage	V_R	V	20	
Die-Attach Temperature		°C	330	60 Seconds Max
Operating Temperature	T_{op}	°C	-40 to 90	
Storage Temperature	T_{stg}	°C	-40 to +100	

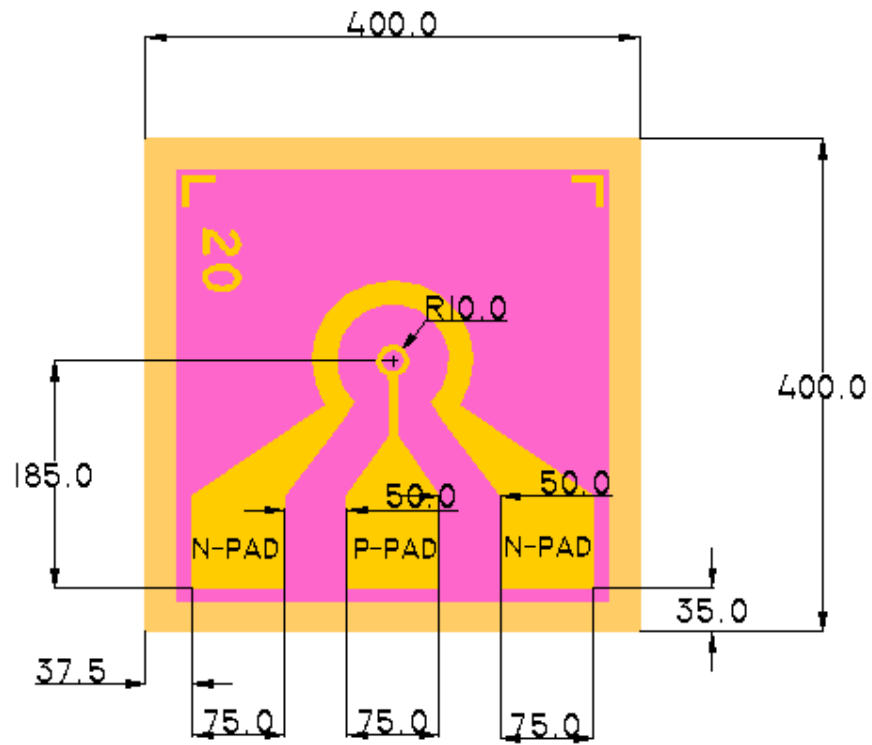


Electro-optical Characteristics (T = 25°C, unless noted otherwise):

Parameter	Symbol	Unit	Min.	Typ.	Max.	Test Condition
Aperture	D	μm	18	20	22	
Responsivity	R	A/W		0.75		$\lambda = 1310 \text{ nm}$
Dark Current	I_D	nA		10	50	$V_R = 5 \text{ V}$
Breakdown Voltage	V_B	V	20			$I_R = 10 \text{ μA}$
Capacitance	C	pF		0.08	0.10	$V_R = 5 \text{ V}$ $f = 1 \text{ MHz}$
Cut-off Frequency	f_c	GHz		22		$V_R = 5 \text{ V}$ $R_L = 50\Omega$

Chip configuration:

1. Top side 50Ω coplanar GSG contact pads.
2. Dimension: 400 μm (width) x 400 μm (length) x 130 μm (thickness)
Tolerance: +/-12.5μm
3. Bond pad size: 75 x 75 μm square



Unit: um

* Specifications are subject to change without notice.
 * Screening per customer-specified reject limits is available.